

Microassembly Workshop-Series, Workshop #1: Industrial need for novel assembly processes

Program on Tuesday, May 10th 2022, 14:00 – ca. 18:00 Swissmem, Pfingstweidstrasse 102, Zurich

Time	Presentation & Topic
14:00 h	Welcome & Introduction Dr. Jörg Güttinger, Managing Director NTN IB-Photonics Dr. Selina Casutt, Head of Department NTN IB-Photonics
14:10 h	Microtechnology Concepts for Miniaturization in Photonic Assembly Dr. Tobias Lamprecht, OST Ostschweizer Fachhochschule
14:25 h	Wafer Scalable Hermetic Sealing of Photonic Components Dr. Stefan Mohrdiek, CSEM SA
14:40 h	Novel Assembly Technique Based on Ultrasonic Technology Dr. Csaba Azau, AAA Assemblage Acoustique Azau
14:55 h	Novel Gripper Solution for Contactless Microhandling Dr. Marcel Schuck, No-Touch Robotics GmbH
15:15 h	Coffee Break
15:45 h	Break-out Discussion Groups: <ol style="list-style-type: none"> Group 1 - <i>Bonding & Packaging - Wafer scalable concepts for photonic components</i>, Moderators: Stefan Mohrdiek & Jörg Güttinger Group 2 - <i>Microtechnology Concepts for Miniaturization in Photonic Assembly</i>, Moderators: Tobias Lamprecht & Selina Casutt Group 3 - <i>Handling & Grippers</i>, Moderators: Marcel Schuck & Werner Krüsi
16:45 h	Podium Discussion
17:15 h	Apéro

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